

ABSTRACT

A probe apparatus includes a mounting member on which an object to be inspected is mounted and a temperature
5 thereof is being adjusted, a probe card arranged opposite to the mounting member, a driving mechanism which changes a relative positional relationship between the mounting member and the probe card, and a sensor which detects the distance between the sensor and the probe card. By way of detecting
10 the height of the deformed probe card through the use of the sensor and revising the elevation distance of the mounting member, the electrode pads of the wafer W and the probe pins can electrically contact each other with a stable pin pressure, providing high inspection reliability and an
15 increase in throughput.